



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GED-531X160HFCA

Test Procedure for a Home Flag Switch card

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Transitioned from GE Canada work instruction to our local shop work instruction format	J. Archibald	2/8/2013
B			
C			

© COPYRIGHT GENERAL ELECTRIC COMPANY

Hard copies are uncontrolled and are for reference only.

PROPRIETARY INFORMATION – THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION OF GENERAL ELECTRIC COMPANY AND MAY NOT BE USED OR DISCLOSED TO OTHERS, EXCEPT WITH THE WRITTEN PERMISSION OF GENERAL ELECTRIC COMPANY.

PREPARED BY J. Archibald	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL <i>Charlie Wade</i>
DATE 2/8/2013	DATE	DATE	DATE 2/8/2013

LOU-GED-531X160HFCA REV. A	g GE Energy Parts & Repair Services Louisville, KY	Page 2 of 3
-------------------------------	------------------------------------------------------------------------	-------------

1. SCOPE

1.1 This is a functional testing procedure for a Home Flag Switch card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)
1		Oscilloscope
1		+15VDC Power Supply
1		Function Generator

LOU-GED-531X160HFCA REV. A	g <i>GE Energy</i> <i>Parts & Repair Services</i> <i>Louisville, KY</i>	Page 3 of 3
-------------------------------	------------------------------------------------------------------------------------------	-------------

6. Modifications/Upgrades

6.1 Fill out if applicable.

7. Testing Process

7.1 Testing Procedure

- 7.1.1 Apply +15VDC to 2TBC with respect to 2TBA=COM.
- 7.1.2 Connect 470Ω to 2TBG and 2TBf.
- 7.1.3 Apply 22Vpp TTL signal at 100Hz to 1TB1 with respect to 1TB4.
- 7.1.4 Note a silver pulse on 2TBf with respect to 2TBA at the same frequency.
- 7.1.5 Move signal from 1TB1 to 1TB6.
- 7.1.6 Note a 41μsec silver pulse on 2TBD.
- 7.1.7 If the mod is added onto card see Pulse on 2TBE.

7.2 ***TEST COMPLETE***

8. Notes

8.1 None at this time.

9. Attachments

9.1 None at this time.